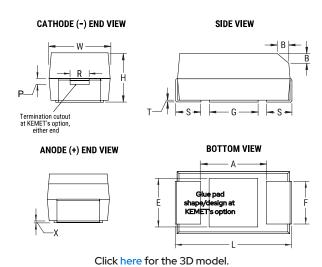


T541X337M010AH6530

Aliases (DLA Drawing 04052-039)

T541 HRA, Tantalum, Polymer Tantalum, HRA Multi-Anode, 330 uF, 20%, 10 VDC, SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR, N/A, 5 mOhms, 7343, 4.3 mm, 1.3 mm



General Information		
Series	T541 HRA	
Dielectric	Polymer Tantalum	
Style	SMD Chip	
Description	SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR	
Features	Non-Combustible, Multiple Anode, Low ESR, High Reliability	
RoHS	No	
Prop 65	WARNING: Cancer and reproductive harm - https://www.p65warnings.ca.gov /	
SCIP Number	b064b03e-bd75-42af-b342-1fe 94dec2340	
Termination	Tin Lead (SnPb)	
Qualifications	DLA Drawing 04052	
AEC-Q200	No	
Typical Component Weight	410.89 mg	
Shelf Life	52 Weeks	
MSL	3	

330 uF

10 VDC (105C), 6.7 VDC (125C)

20%

Dimensions	
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
Н	4mm +/-0.3mm
T	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.8mm MIN
В	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
Р	1.7mm REF
R	1mm REF
Χ	0.1mm +/-0.1mm REF

T&R, 178mm

500

Packaging

Packaging Quantity

Т	0.13mm REF	Temperature Range	-55/+125°C
S	1.3mm +/-0.3mm	Rated Temperature	105°C
F	2.4mm +/-0.1mm	Life	2000 Hrs (125C)
A	3.8mm MIN	Humidity	60C, 90% RH, 500 Hours, rated voltage
В	0.5mm +/-0.15mm		3
E	3.5mm REF	Dissipation Factor	10% 120Hz 25C
6	3.5mm REF	Failure Rate	N/A
G		ESR	5 mOhms (100kHz 25C)
P	1.7mm REF	Discribe Comment	72.40 4 (1001-1 - 450)
R	1mm REF	Ripple Current	7348 mA (rms, 100kHz 45C)
0.1mm +/-0.1mm REF	Leakage Current	330 uA (5min 25°C)	
	Testing and Reliability	4 Cycles At +25C +/-5C Before Voltage Aging	
Packaging Specifications			3 3 3
·			

Specifications

Capacitance Tolerance

Voltage DC

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 08/24/2025 © 2006 - 2025 YAGEO



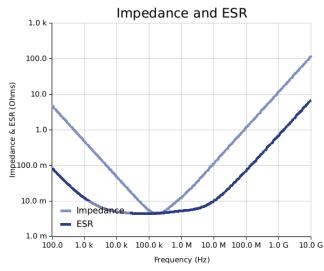
T541X337M010AH6530

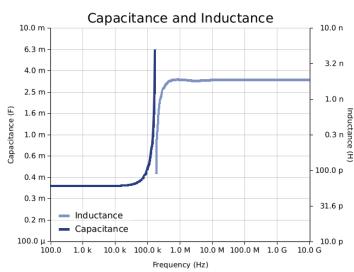
Aliases (DLA Drawing 04052-039)

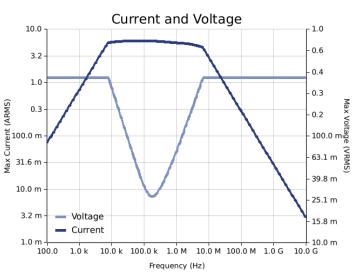
T541 HRA, Tantalum, Polymer Tantalum, HRA Multi-Anode, 330 uF, 20%, 10 VDC, SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR, N/A, 5 mOhms, 7343, 4.3 mm, 1.3 mm

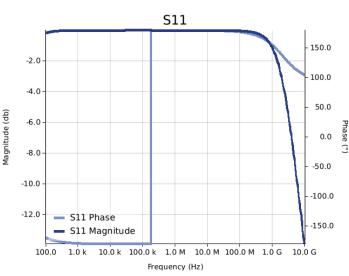
Simulations

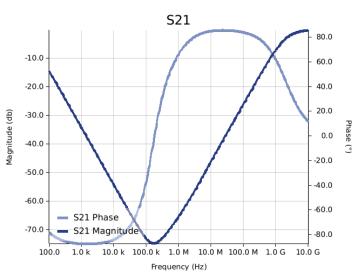
For the complete simulation environment please visit Y-SIM.











Generated 08/24/2025 © 2006 - 2025 YAGEO



T541X337M010AH6530

Aliases (DLA Drawing 04052-039)

T541 HRA, Tantalum, Polymer Tantalum, HRA Multi-Anode, 330 uF, 20%, 10 VDC, SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR, N/ A, 5 mOhms, 7343, 4.3 mm, 1.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question.

 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

Generated 08/24/2025 © 2006 - 2025 YAGEO